

# GaAlAs-IR-Lumineszenzdioden (880 nm) in SMR® Gehäuse

GaAlAs Infrared Emitters (880 nm) in SMR® Package

Lead (Pb) Free Product - RoHS Compliant

**SFH 4580**

**SFH 4585**



SFH 4580



SFH 4585

## Wesentliche Merkmale

- GaAlAs-LED mit sehr hohem Wirkungsgrad
- SMR® (Surface Mount Radial) Gehäuse
- Für Oberflächenmontage geeignet
- Gegurtet lieferbar
- Gehäusegleich mit Fotodiode SFH 2500/ SFH 2505
- Hohe Zuverlässigkeit
- Gute spektrale Anpassung an Si-Fotoempfänger
- UL-Freigabe

## Features

- Very highly efficient GaAlAs-LED
- SMR® (Surface Mount Radial) package
- Suitable for surface mounting (SMT)
- Available on tape and reel
- Same package as photodiode SFH 2500/ SFH 2505
- High reliability
- Spectral match with silicon photodetectors
- UL-approval

## Anwendungen

- IR-Fernsteuerung von Fernseh- und Rundfunkgeräten, Videorecordern, Lichtdimmern
- Gerätefernsteuerungen für Gleich- und Wechsellichtbetrieb
- Sensorik
- Diskrete Lichtschranken
- Diskrete Optokoppler

## Applications

- IR remote control of hi-fi and TV-sets, video tape recorders, dimmers
- Remote control for steady and varying intensity
- Sensor technology
- Discrete interrupters
- Discrete optocouplers

Typ Type	Bestellnummer Ordering Code	Strahlstärkegruppierung <sup>1)</sup> ( $I_F = 100 \text{ mA}$ , $t_p = 20 \text{ ms}$ ) Radiant Intensity Grouping <sup>1)</sup> $I_e$ (mW/sr)
SFH 4580	Q65110A2632	$\geq 25$ (typ. 55)
SFH 4585	Q65110A2631	

<sup>1)</sup> gemessen bei einem Raumwinkel  $\Omega = 0.01 \text{ sr}$  / measured at a solid angle of  $\Omega = 0.01 \text{ sr}$

**Grenzwerte ( $T_A = 25^\circ\text{C}$ )****Maximum Ratings**

<b>Bezeichnung Parameter</b>	<b>Symbol Symbol</b>	<b>Wert Value</b>	<b>Einheit Unit</b>
Betriebs- und Lagertemperatur Operating and storage temperature range	$T_{\text{op}}, T_{\text{stg}}$	- 40 ... + 100	°C
Sperrspannung Reverse voltage	$V_R$	5	V
Durchlassstrom Forward current	$I_F$	100	mA
Stoßstrom, $t_p = 10 \mu\text{s}, D = 0$ Surge current	$I_{\text{FSM}}$	2.5	A
Verlustleistung Power dissipation	$P_{\text{tot}}$	200	mW
Wärmewiderstand Sperrsicht - Umgebung bei Montage auf FR4 Platine, Padgröße je 20 mm <sup>2</sup> Thermal resistance junction - ambient mounted on PC-board (FR4), padsize 20 mm <sup>2</sup> each	$R_{\text{thJA}}$	375	K/W

**Kennwerte ( $T_A = 25^\circ\text{C}$ )****Characteristics**

<b>Bezeichnung Parameter</b>	<b>Symbol Symbol</b>	<b>Wert Value</b>	<b>Einheit Unit</b>
Wellenlänge der Strahlung Wavelength at peak emission $I_F = 100 \text{ mA}$	$\lambda_{\text{peak}}$	880	nm
Spektrale Bandbreite bei 50% von $I_{\text{rel}}$ Spectral bandwidth at 50% of $I_{\text{rel}}$ $I_F = 100 \text{ m A}$	$\Delta\lambda$	80	nm
Abstrahlwinkel Half angle	$\varphi$	± 15	Grad deg.
Aktive Chipfläche Active chip area	$A$	0.09	mm <sup>2</sup>
Abmessungen der aktiven Chipfläche Dimension of the active chip area	$L \times B$ $L \times W$	0.3 × 0.3	mm <sup>2</sup>
Abstand Chipoberfläche bis Linsenscheitel Distance chip front to lens top	$H$	3.9 ... 4.5	mm

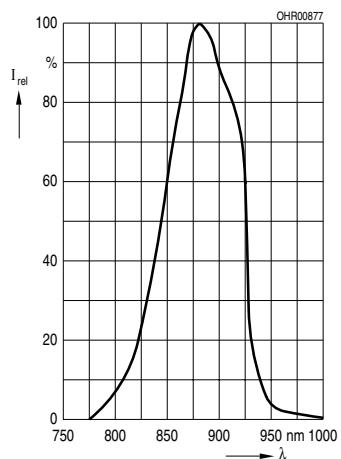
**Kennwerte ( $T_A = 25^\circ\text{C}$ )****Characteristics (cont'd)**

Bezeichnung Parameter	Symbol Symbol	Wert Value	Einheit Unit
Schaltzeiten, $I_e$ von 10% auf 90% und von 90% auf 10%, bei $I_F = 100 \text{ mA}$ , $R_L = 50 \Omega$ Switching times, $I_e$ from 10% to 90% and from 90% to 10%, $I_F = 100 \text{ mA}$ , $R_L = 50 \Omega$	$t_r, t_f$	0.6/0.5	$\mu\text{s}$
Kapazität Capacitance $V_R = 0 \text{ V}, f = 1 \text{ MHz}$	$C_o$	15	pF
Durchlassspannung Forward voltage $I_F = 100 \text{ mA}, t_p = 20 \text{ ms}$ $I_F = 1 \text{ A}, t_p = 100 \mu\text{s}$	$V_F$ $V_F$	1.50 ( $\leq 1.8$ ) 3.00 ( $\leq 3.8$ )	V V
Sperrstrom Reverse current $V_R = 5 \text{ V}$	$I_R$	0.01 ( $\leq 1$ )	$\mu\text{A}$
Gesamtstrahlungsfluss Total radiant flux $I_F = 100 \text{ mA}, t_p = 20 \text{ ms}$	$\Phi_e$	25	mW
Temperaturkoeffizient von $I_e$ bzw. $\Phi_e$ , $I_F = 100 \text{ mA}$ Temperature coefficient of $I_e$ or $\Phi_e$ , $I_F = 100 \text{ mA}$	$TC_I$	- 0.5	%/K
Temperaturkoeffizient von $V_F$ , $I_F = 100 \text{ mA}$ Temperature coefficient of $V_F$ , $I_F = 100 \text{ mA}$	$TC_V$	- 2	mV/K
Temperaturkoeffizient von $\lambda$ , $I_F = 100 \text{ mA}$ Temperature coefficient of $\lambda$ , $I_F = 100 \text{ mA}$	$TC_\lambda$	0.25	nm/K

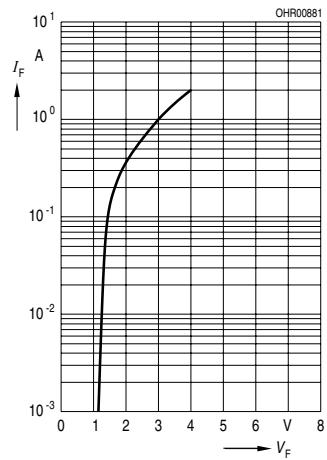
**Strahlstärke  $I_e$  in Achsrichtung**gemessen bei einem Raumwinkel  $\Omega = 0.01 \text{ sr}$ **Radiant Intensity  $I_e$  in Axial Direction**at a solid angle of  $\Omega = 0.01 \text{ sr}$ 

Bezeichnung Parameter	Symbol	Wert Value	Einheit Unit
Strahlstärke Radiant intensity $I_F = 100 \text{ mA}, t_p = 20 \text{ ms}$	$I_{e \min}$ $I_{e \text{ typ}}$	25 55	mW/sr mW/sr
Strahlstärke Radiant intensity $I_F = 1 \text{ A}, t_p = 100 \mu\text{s}$	$I_{e \text{ typ}}$	500	mW/sr

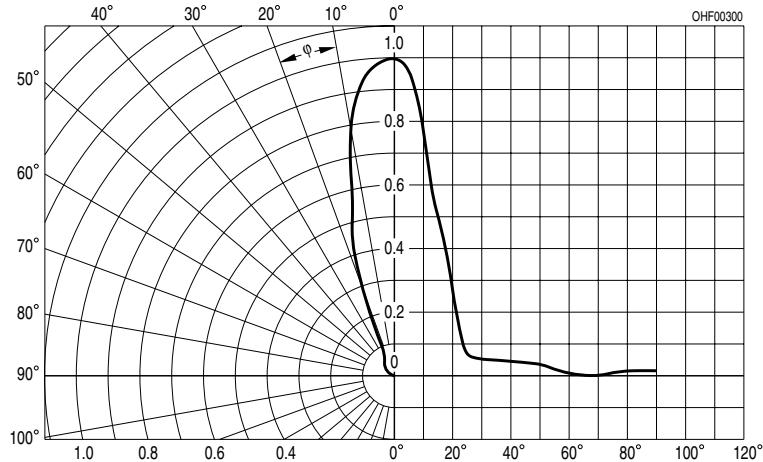
**Relative Spectral Emission**  
 $I_{\text{rel}} = f(\lambda)$



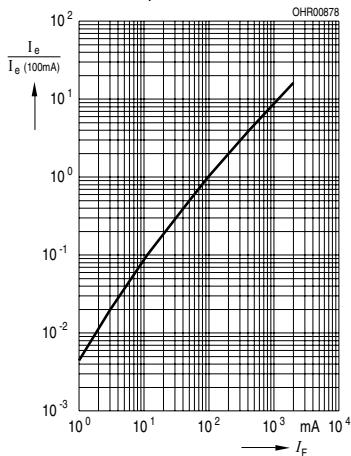
**Forward Current**  
 $I_F = f(V_F)$ , single pulse,  $t_p = 20 \mu\text{s}$



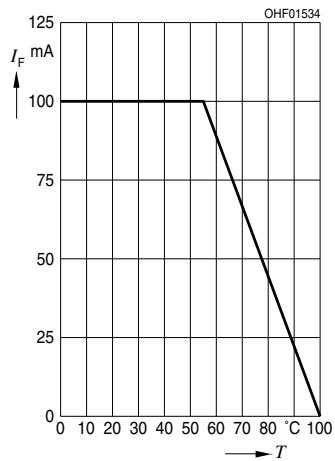
**Radiation Characteristics**  $I_{\text{rel}} = f(\phi)$



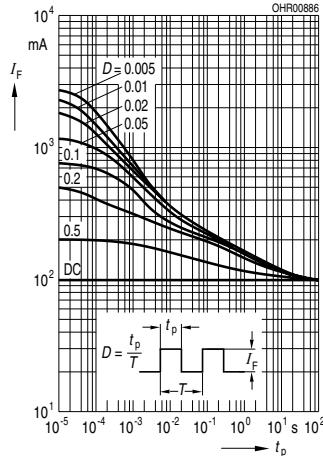
**Radiant Intensity**  $\frac{I_e}{I_e \text{ 100 mA}} = f(I_F)$   
Single pulse,  $t_p = 20 \mu\text{s}$



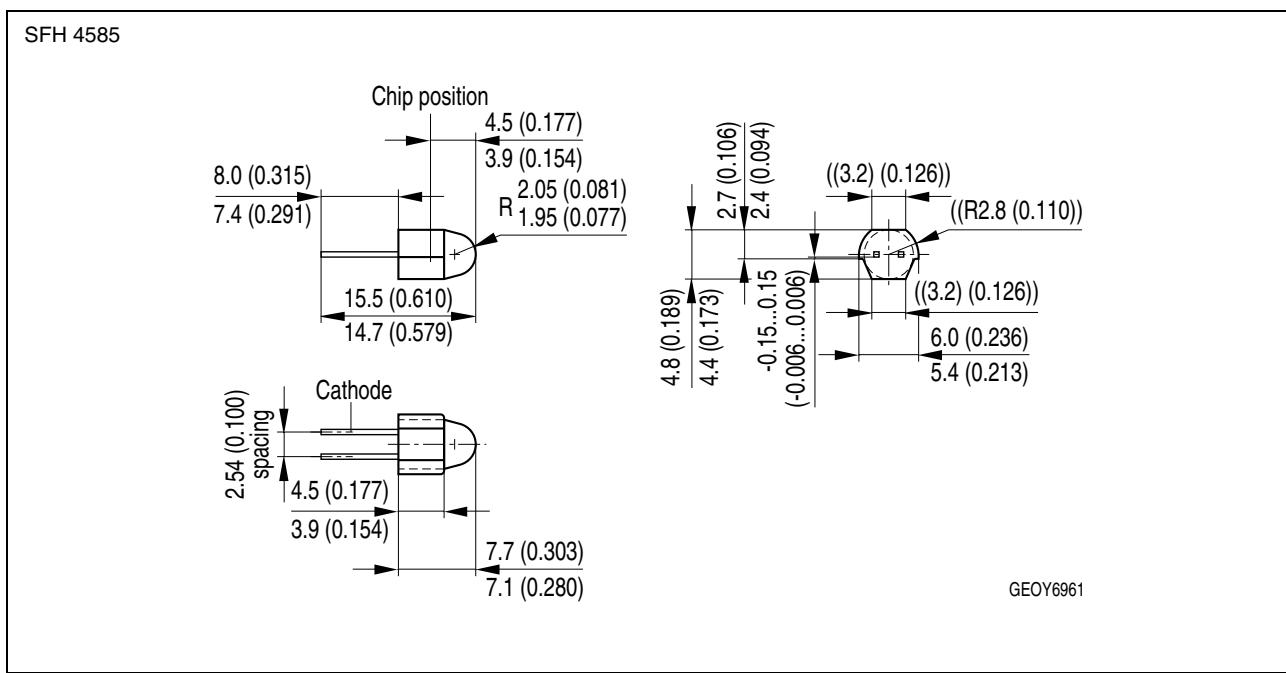
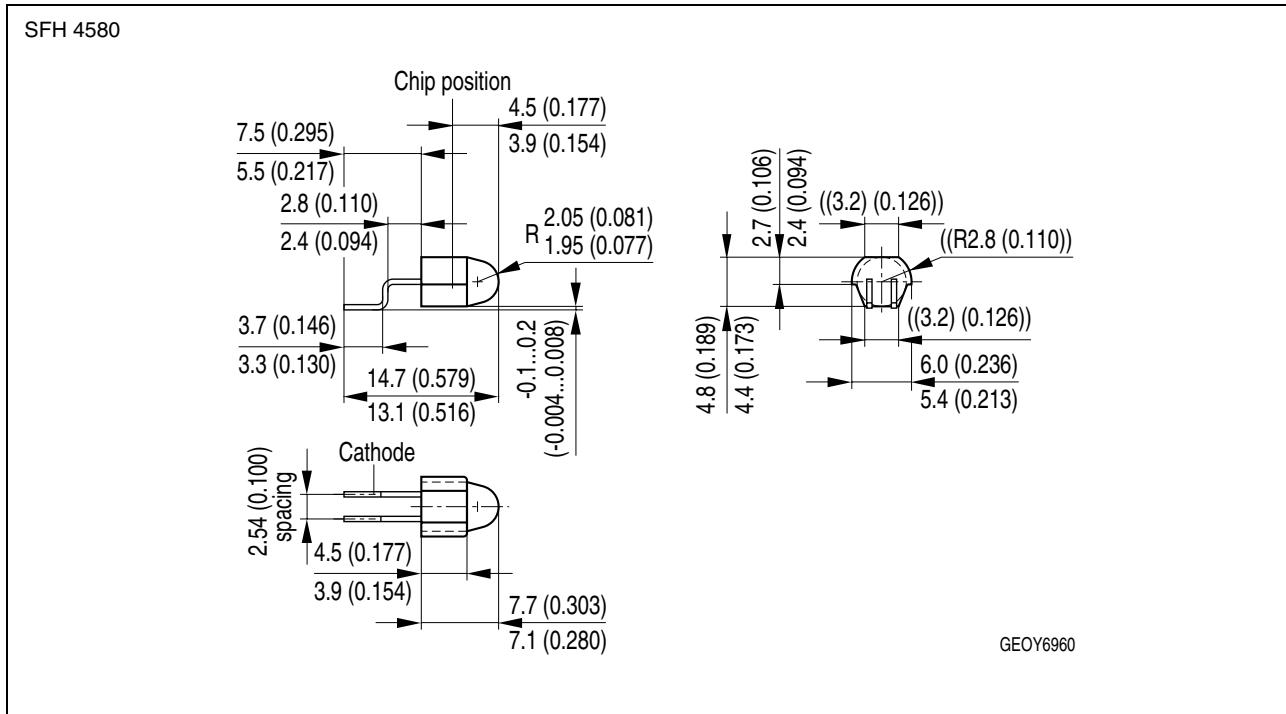
**Max. Permissible Forward Current**  
 $I_F = f(T_A)$



**Permissible Pulse Handling Capability**  $I_F = f(\tau)$ ,  $T_A = 25^\circ\text{C}$ , duty cycle  $D$  = parameter



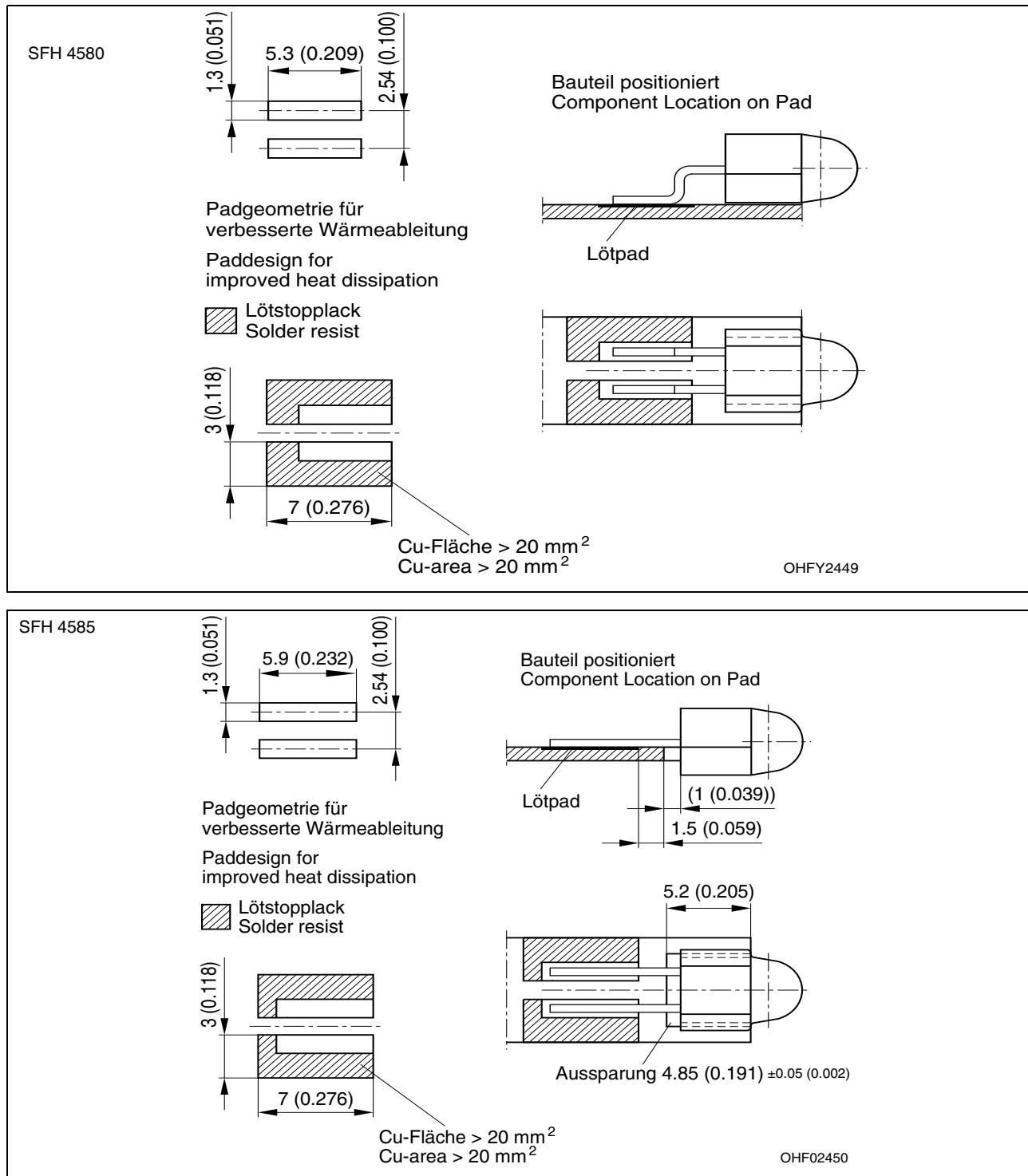
**Maßzeichnung  
Package Outlines**



Maße in mm (inch) / Dimensions in mm (inch).

**Empfohlenes Lötpaddesign**  
Recommended Solder Pad

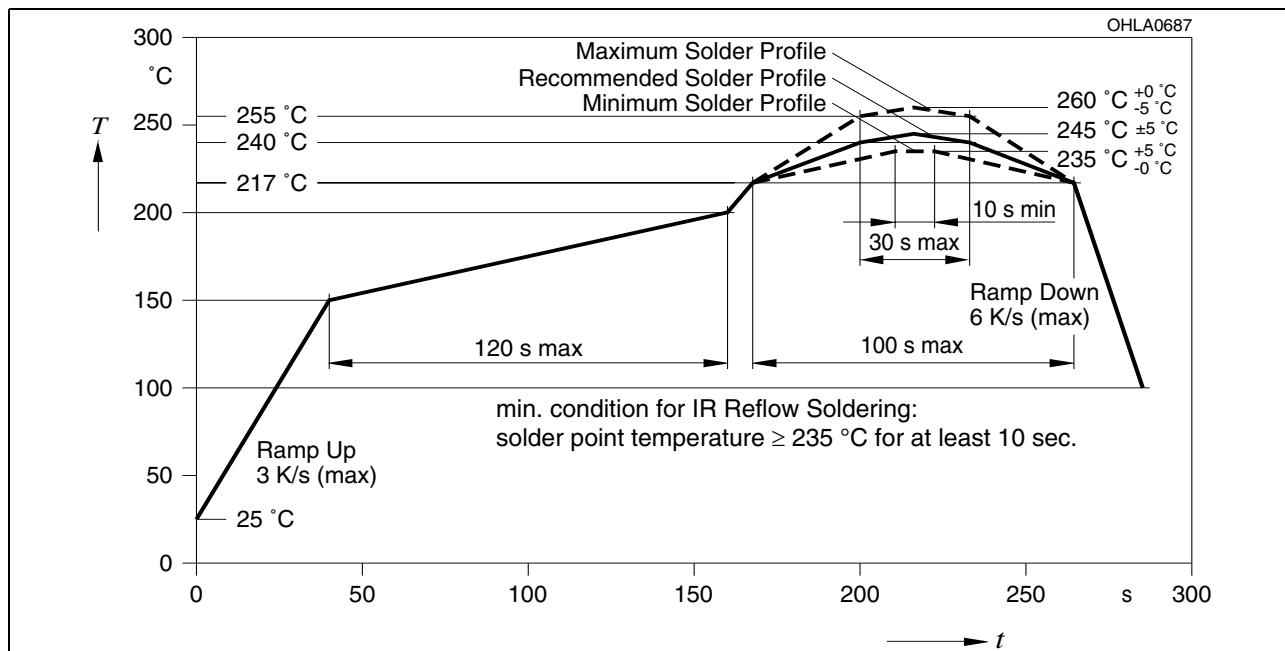
Reflow Löten  
Reflow Soldering



Maße in mm (inch) / Dimensions in mm (inch).

**Lötbedingungen****Soldering Conditions****Reflow Lötprofil für bleifreies Löten****Reflow Soldering Profile for lead free soldering**

Vorbehandlung nach JEDEC Level 3  
 Preconditioning acc. to JEDEC Level 3  
 (nach J-STD-020C)  
 (acc. to J-STD-020C)



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